

## P-Channel NexFET™ Power MOSFET

Check for Samples: [CSD25211W1015](#)

### FEATURES

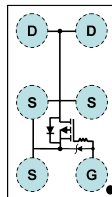
- Ultra Low On Resistance
- Ultra Low Qg and Qgd
- Small Footprint 1.0mm x 1.5mm
- Low Profile 0.62mm Height
- Pb Free
- Gate-Source Voltage Clamp
- Gate ESD Protection - 3KV
- RoHS Compliant
- Halogen Free

### APPLICATIONS

- Battery Management
- Load Switch
- Battery Protection

### DESCRIPTION

The device has been designed to deliver the lowest on resistance and gate charge in the smallest outline possible with excellent thermal characteristics in an ultra low profile.

**Top View**


### PRODUCT SUMMARY

T <sub>A</sub> = 25°C unless otherwise stated		TYPICAL VALUE		UNIT
V <sub>DS</sub>	Drain to Source Voltage	-20		V
Q <sub>g</sub>	Gate Charge Total (-4.5V)	3.4		nC
Q <sub>gd</sub>	Gate Charge Gate to Drain	0.2		nC
R <sub>DS(on)</sub>	Drain to Source On Resistance	V <sub>GS</sub> = -2.5V	36	mΩ
		V <sub>GS</sub> = -4.5V	27	mΩ
V <sub>GS(th)</sub>	Voltage Threshold	-0.8		V

### ORDERING INFORMATION

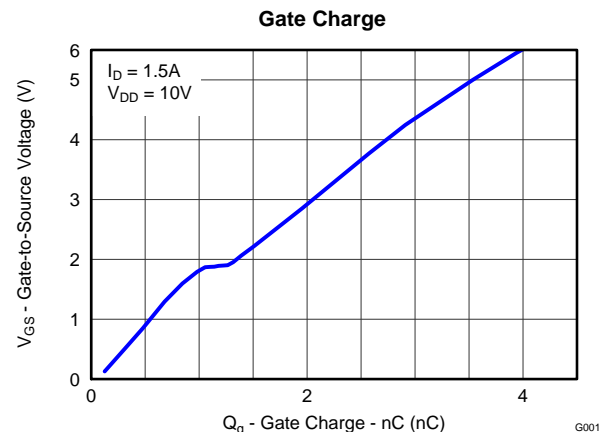
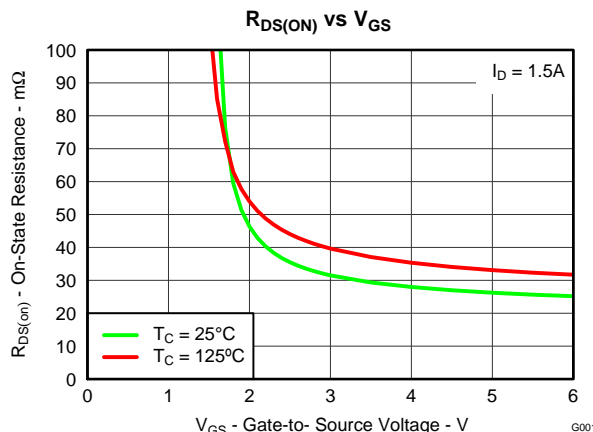
Device	Package	Media	Qty	Ship
CSD25211W1015	1 × 1.5 Wafer Level Package	7-inch reel	3000	Tape and Reel

### ABSOLUTE MAXIMUM RATINGS

T <sub>A</sub> = 25°C unless otherwise stated		VALUE	UNIT
V <sub>DS</sub>	Drain to Source Voltage	-20	V
V <sub>GS</sub>	Gate to Source Voltage	-6	V
I <sub>D</sub>	Continuous Drain Current, T <sub>A</sub> = 25°C <sup>(1)</sup>	-3.2	A
I <sub>DM</sub>	Pulsed Drain Current, T <sub>A</sub> = 25°C <sup>(2)</sup>	-9.5	A
I <sub>G</sub>	Continuous Drain Current, T <sub>A</sub> = 25°C	-0.5	A
	Pulsed Drain Current	-7	A
P <sub>D</sub>	Power Dissipation <sup>(1)</sup>	1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range		

(1) Typical R<sub>θJA</sub> = 119°C/W on 1 inch<sup>2</sup> of 2 oz. Cu on 0.06" thick FR4 PCB.

(2) Pulse width ≤10μs, duty cycle ≤2%



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ELECTRICAL CHARACTERISTICS

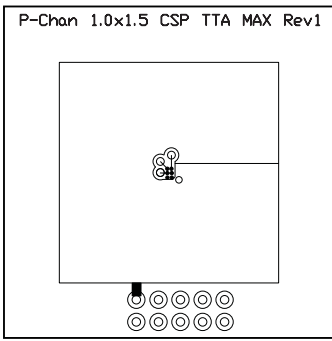
( $T_A = 25^\circ\text{C}$  unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Static Characteristics</b>						
$V_{DSS}$	Drain to Source Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
$V_{GSS}$	Gate to Source Voltage	$V_{DS} = 0V, I_G = -250\mu A$	-6.1		-7.2	V
$I_{DSS}$	Drain to Source Leakage Current	$V_{GS} = 0V, V_{DS} = -16V$			-1	$\mu A$
$I_{GSS}$	Gate to Source Leakage Current	$V_{DS} = 0V, V_{GS} = -6V$			-100	nA
$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.5	-0.8	-1.1	V
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = -2.5V, I_D = -1.5A$		36	44	$m\Omega$
		$V_{GS} = -4.5V, I_D = -1.5A$		27	33	$m\Omega$
$g_{fs}$	Transconductance	$V_{DS} = -10V, I_D = -1.5A$		12		S
<b>Dynamic Characteristics</b>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0V, V_{DS} = -10V, f = 1MHz$		475	570	pF
$C_{OSS}$	Output Capacitance			234	281	pF
$C_{RSS}$	Reverse Transfer Capacitance			10.5	13.1	pF
$Q_g$	Gate Charge Total (-4.5V)	$V_{DS} = -10V, I_D = -1.5A$		3.4	4.1	nC
$Q_{gd}$	Gate Charge Gate to Drain			0.2		nC
$Q_{gs}$	Gate Charge Gate to Source			1.1		nC
$Q_{g(th)}$	Gate Charge at $V_{th}$			0.6		nC
$Q_{OSS}$	Output Charge	$V_{DS} = -10V, V_{GS} = 0V$		3.8		nC
$t_{d(on)}$	Turn On Delay Time	$V_{DS} = -10V, V_{GS} = -4.5V, I_D = -1.5A$ $R_G = 4\Omega$		13.6		ns
$t_r$	Rise Time			8.8		ns
$t_{d(off)}$	Turn Off Delay Time			36.9		ns
$t_f$	Fall Time			14.2		ns
<b>Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_S = -1.5A, V_{GS} = 0V$		-0.8	-1	V
$Q_{rr}$	Reverse Recovery Charge	$V_{dd} = -10V, I_F = -1.5A, di/dt = 200A/\mu s$		6.9		nC
$t_{rr}$	Reverse Recovery Time			11.6		ns

## THERMAL CHARACTERISTICS

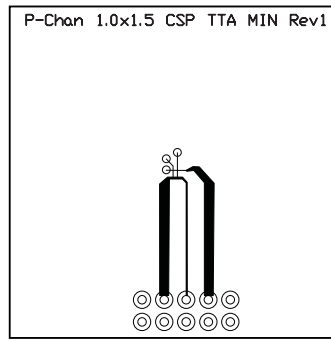
( $T_A = 25^\circ\text{C}$  unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (Minimum Cu area)			230	$^\circ\text{C/W}$
	Thermal Resistance Junction to Ambient (1 in <sup>2</sup> Cu area)			149	$^\circ\text{C/W}$



Max  $R_{\theta JA} = 149^{\circ}\text{C/W}$   
when mounted on 1  
 $\text{inch}^2$  of 2 oz. Cu.

M0155-01



Max  $R_{\theta JA} = 230^{\circ}\text{C/W}$   
when mounted on  
minimum pad area of 2  
oz. Cu.

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### TYPICAL MOSFET CHARACTERISTICS

( $T_A = 25^{\circ}\text{C}$  unless otherwise stated)

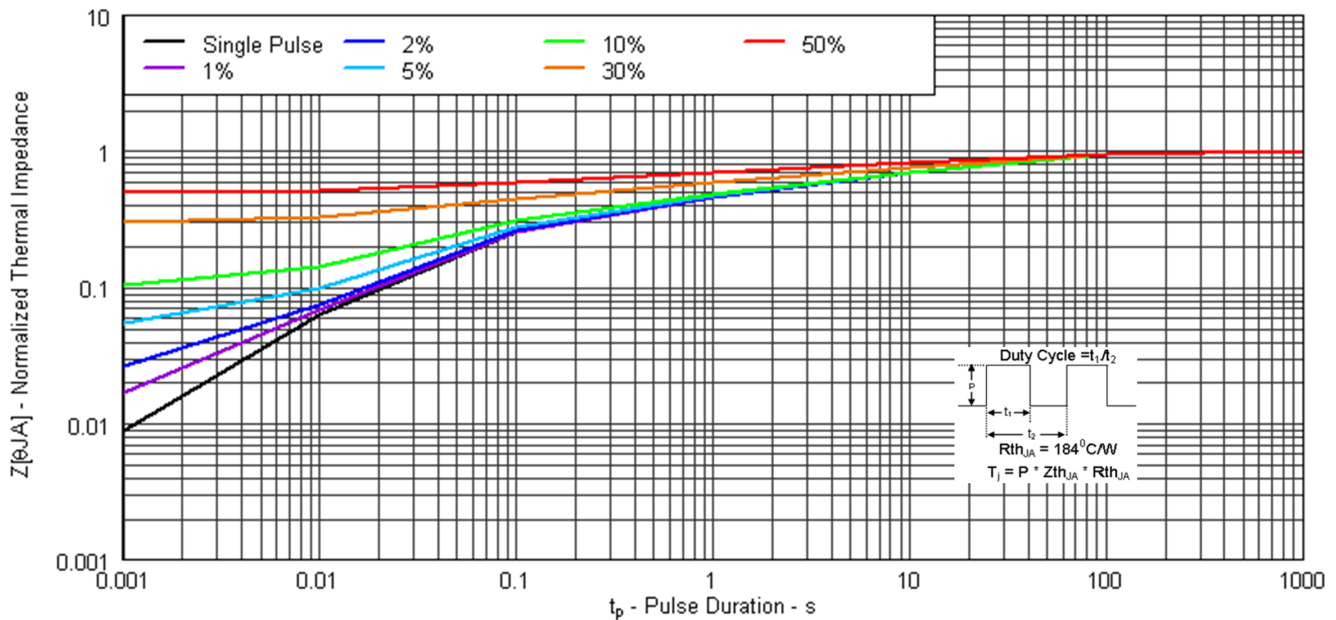
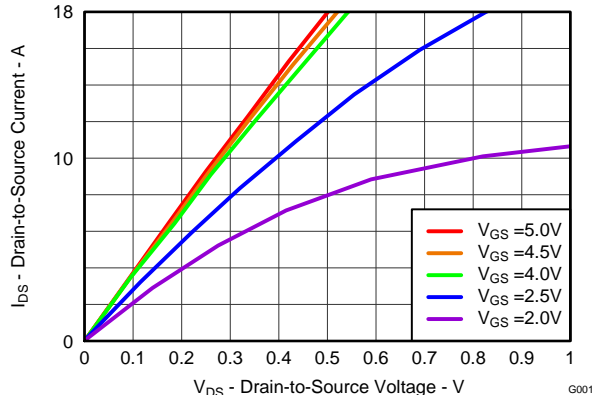


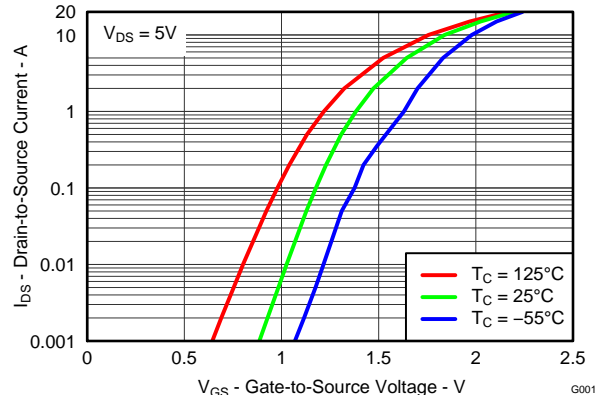
Figure 1. Transient Thermal Impedance

**TYPICAL MOSFET CHARACTERISTICS (continued)**

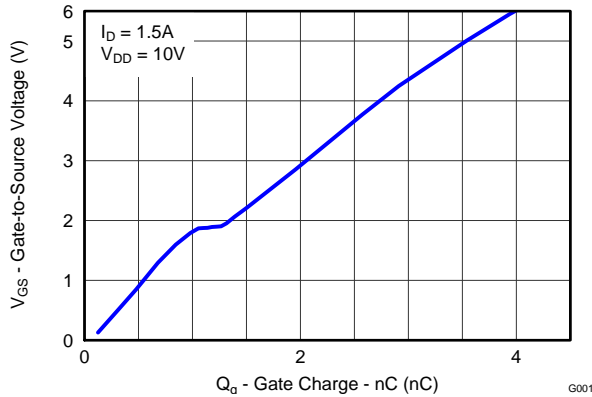
( $T_A = 25^\circ\text{C}$  unless otherwise stated)



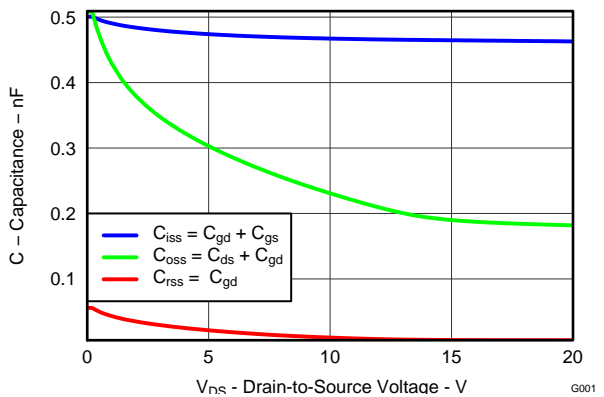
**Figure 2. Saturation Characteristics**



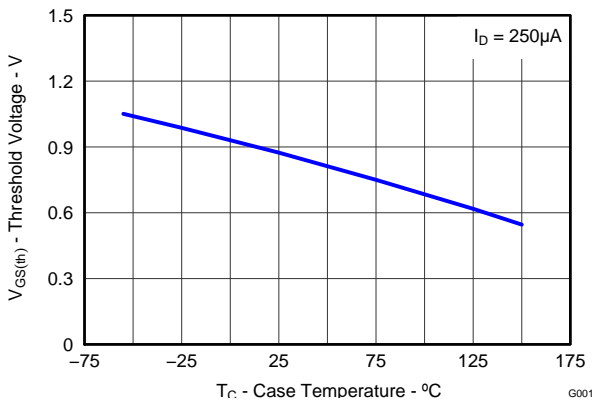
**Figure 3. Transfer Characteristics**



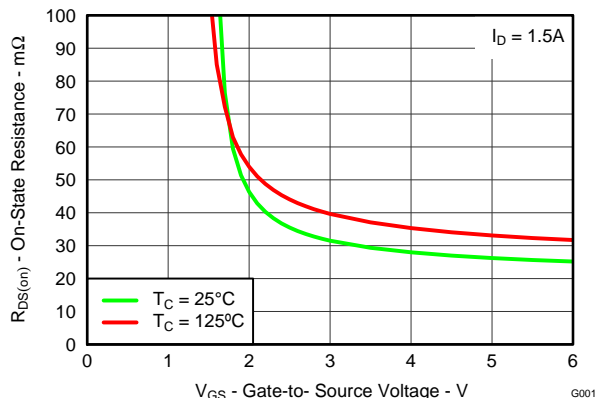
**Figure 4. Gate Charge**



**Figure 5. Capacitance**



**Figure 6. Threshold Voltage vs. Temperature**



**Figure 7. On Resistance vs. Gate Voltage**

TYPICAL MOSFET CHARACTERISTICS (continued)

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

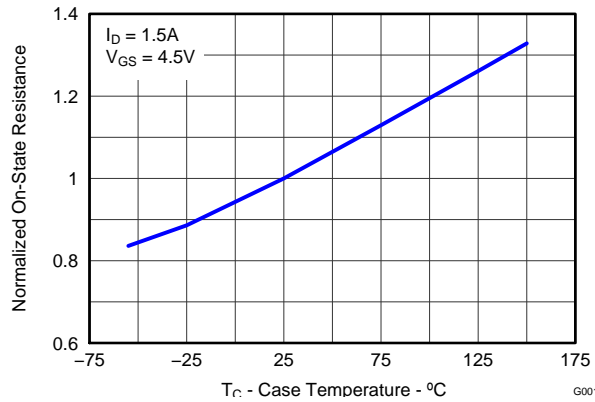


Figure 8. Normalized On Resistance vs. Temperature

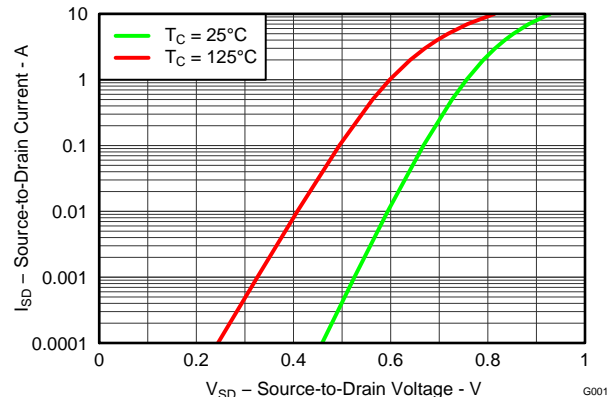


Figure 9. Typical Diode Forward Voltage

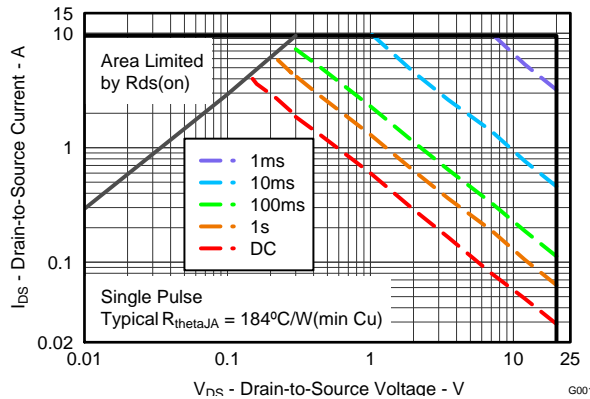


Figure 10. Maximum Safe Operating Area

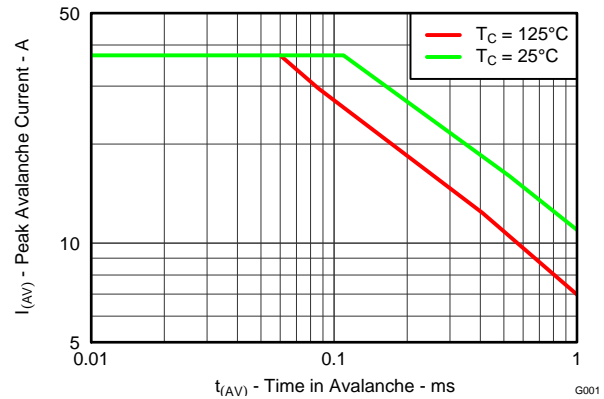


Figure 11. Single Pulse Unclamped Inductive Switching

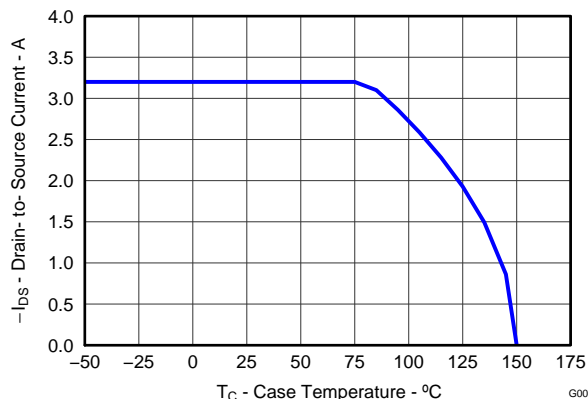
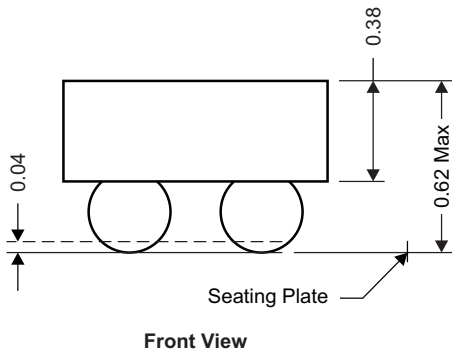
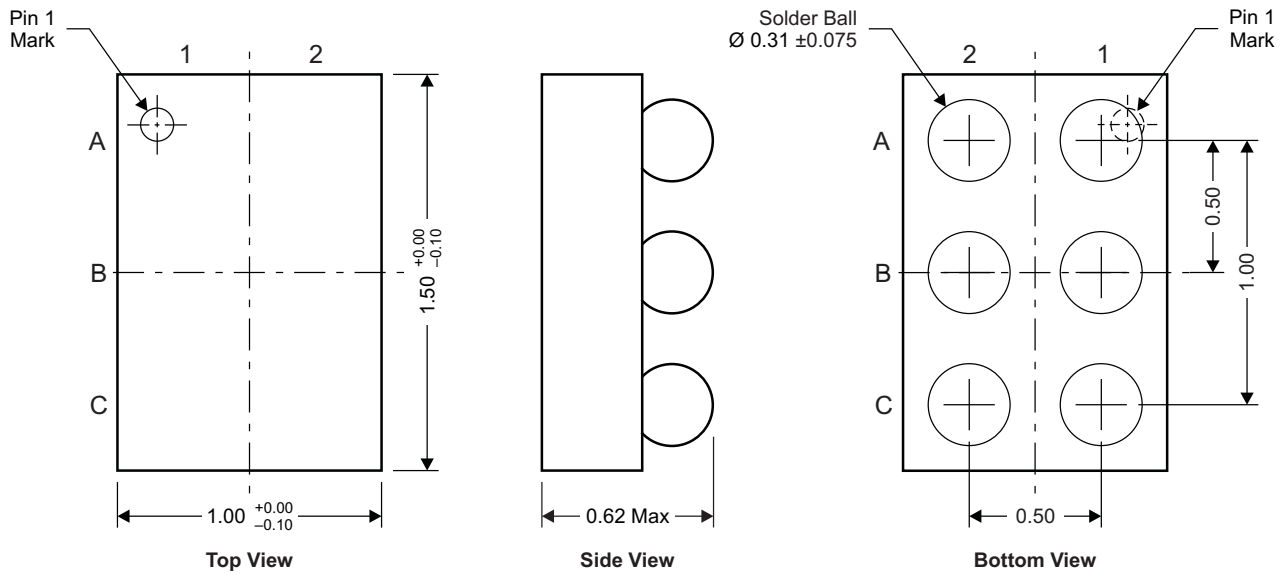


Figure 12. Maximum Drain Current vs. Temperature

**MECHANICAL DATA**

**CSD25211W1015 Package Dimensions**



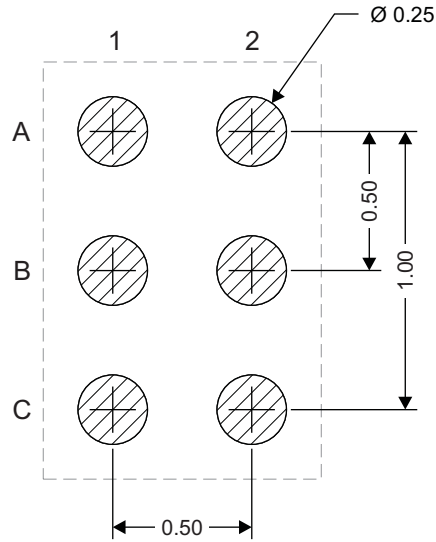
NOTE: All dimensions are in mm (unless otherwise specified)

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**Pinout**

POSITION	DESIGNATION
C1, C2	Drain
A1	Gate
A2, B1, B2	Source

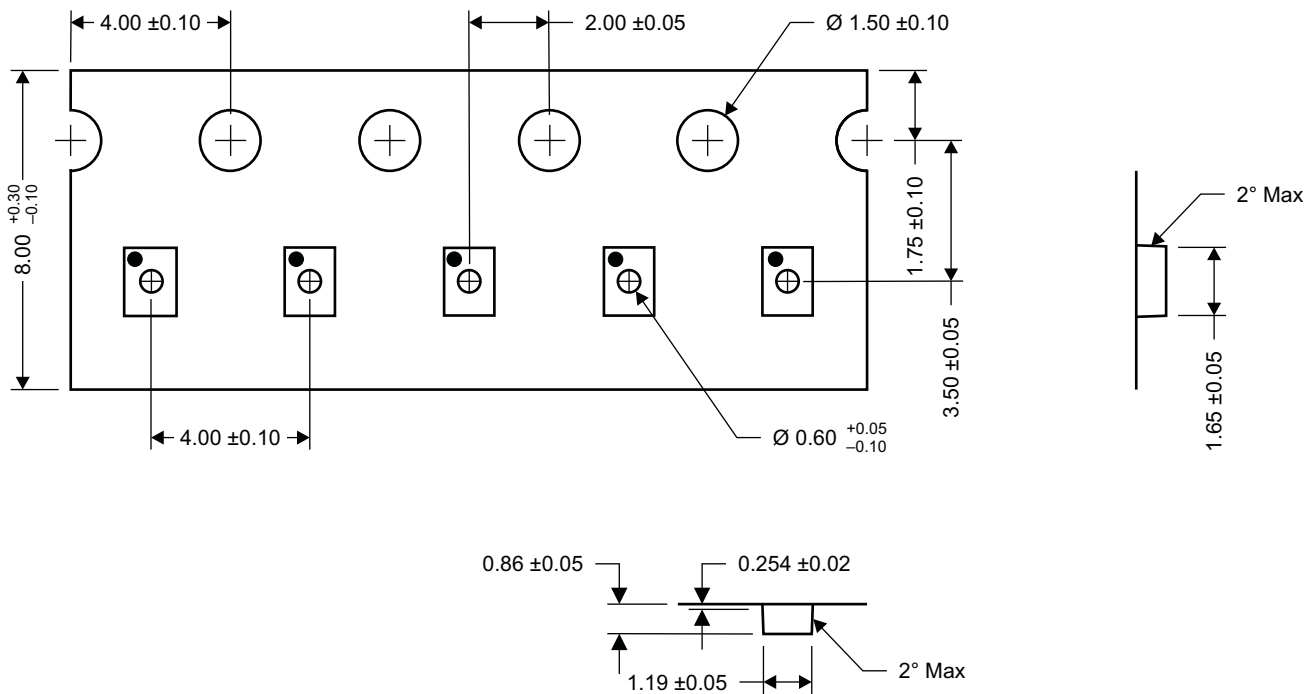
**Land Pattern Recommendation**



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NOTE: All dimensions are in mm (unless otherwise specified)

**Tape and Reel Information**



M0159-01

NOTE: All dimensions are in mm (unless otherwise specified)

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CSD25211W1015	ACTIVE	DSBGA	YZC	6	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-55 to 150	25211	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

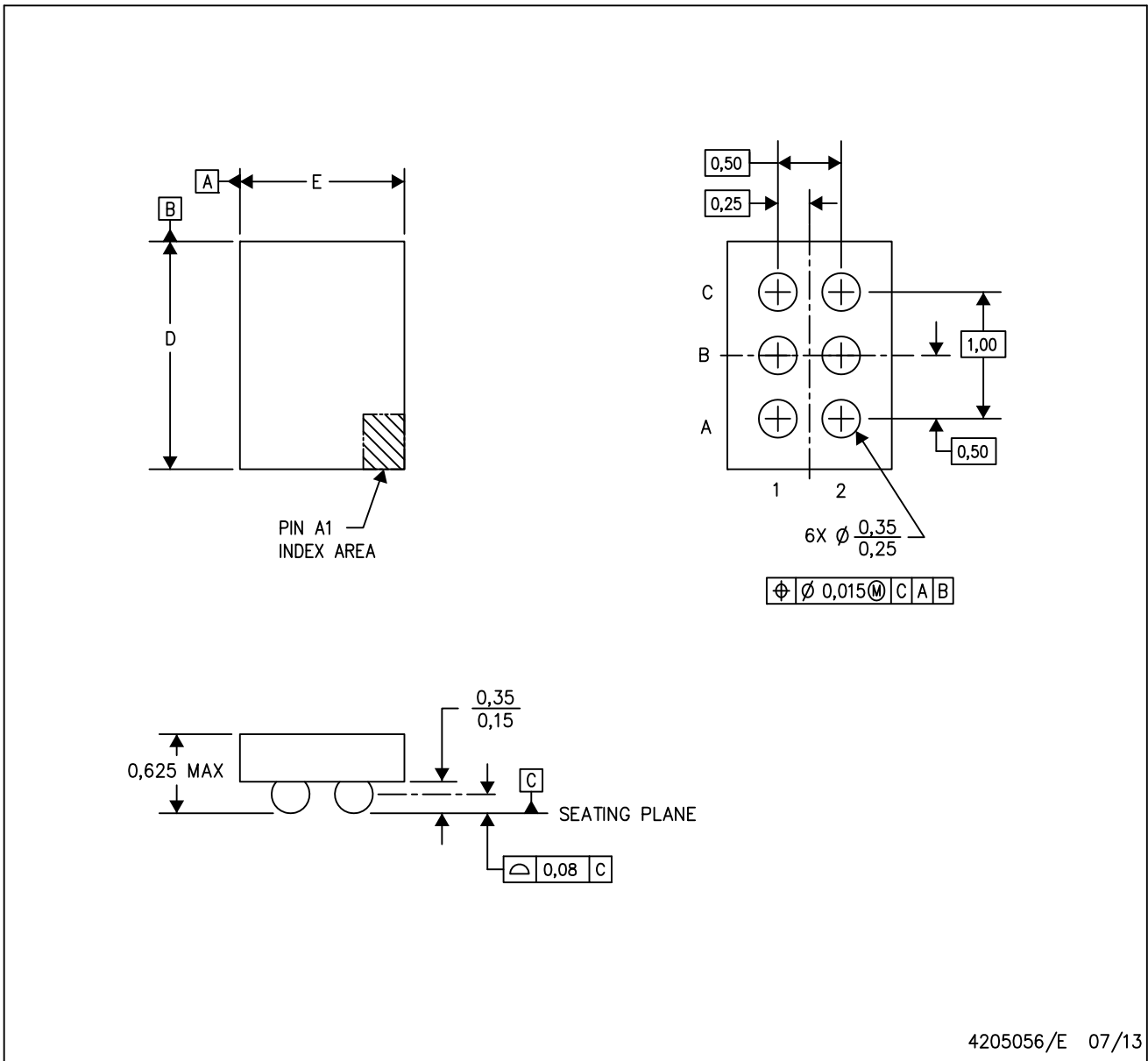
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YZC (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.  
 B. This drawing is subject to change without notice.  
 C. NanoFree™ package configuration.

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Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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